



specifications

Items	Parameters
Surface treatment	HAL (Tin/Lead), SN100C, Gold plating, Immersion Gold, Immersion Tin, Immersion Silver, Hard Gold, OSP
Account of layers	Single sided, Double side and multi-layers (upto 40-layers)
Min. trace width	0,076 mm (3 mil)
Min. trace space	0,076 mm (3 mil)
Min. space between trace to pads, pads to pads	0,076 mm (3 mil)
Min. mechanical drill hole diameter	0,10 mm (4mil)
Min. laser drill hole diameter	0,10 mm (4 mil)
Min. pads for vias	0,30 mm (12 mil)
Max. aspect ratio	1:20
Max. PCB dimension	584,2 x 889,0 mm
PCB thickness	0,13 -7,0 mm
Max. copper weight	175 micron
Solder mask bridge between solder dam	0,10 mm (4 mil)
Min. soldermask annular	0,038 mm (1,5 mil)
Soldermask colors	Black, Blue, Green, White, Yellow, Transparance LPI Soldermask AND peelable Soldermask
Min. width of legend	0,10 mm (4 mil)
Min. height of legend	0,635 mm (25 mil)
Min. plugged holes size	0,2 mm
Max. plugged holes size	0,65 mm
Legend colors	White, Yellow, Black
Data format	GERBER, PROTEL, PADS2000, Powerpcb, ODB++
Electric test	100% E-test, high voltage test (=impedance control)
Special material	HiTg FR4, High Frequency (Rogers, Teflon, RF35, Arlon), Free Halogen, Different materials mixing laminating
Other test	Impedance Control, Resistor of hole test, Micro section, Ionic cleanliness test; Soldering capacity, thermal shocking, reliability test etc.
Special technisues	Blind and buried via's (min holes size is 0,1 mm), Multi-layer with heavy copper